

Title (en)
SYSTEM-ON-FOIL DEVICE

Title (de)
SYSTEM-ON-FOIL-VORRICHTUNG

Title (fr)
DISPOSITIF DE SYSTÈME SUR FEUILLE

Publication
EP 4039069 A4 20231108 (EN)

Application
EP 20870870 A 20201005

Priority
• US 201962910076 P 20191003
• US 2020054245 W 20201005

Abstract (en)
[origin: WO2021067927A1] A device includes an electrically conductive substrate, one or more intermediate layer(s) in contact with the electrically conductive substrate and/or one or more interconnect layer, and a surface mounted electrical component contacting the interconnect layer.

IPC 8 full level
H05K 3/46 (2006.01); **H01L 23/14** (2006.01)

CPC (source: EP KR US)
H01L 23/142 (2013.01 - EP US); **H01L 23/3157** (2013.01 - US); **H01L 23/5283** (2013.01 - US); **H01L 23/53209** (2013.01 - US);
H05K 1/053 (2013.01 - EP KR); **H05K 3/4673** (2013.01 - KR); **H05K 3/4676** (2013.01 - EP); **H05K 3/44** (2013.01 - EP KR);
H05K 3/4608 (2013.01 - EP KR)

Citation (search report)
• [XAY] DE 4444567 A1 19960605 - SIEMENS AG [DE]
• [XAY] WO 2015071636 A1 20150521 - CAMBRIDGE NANOTHERM LTD [GB]
• [XAY] WO 2016073068 A1 20160512 - SEMICONDUCTOR COMPONENTS IND [US]
• See references of WO 2021067927A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
WO 2021067927 A1 20210408; CN 114667807 A 20220624; EP 4039069 A1 20220810; EP 4039069 A4 20231108; JP 2022551115 A 20221207;
KR 20220070531 A 20220531; US 2023060965 A1 20230302

DOCDB simple family (application)
US 2020054245 W 20201005; CN 202080069214 A 20201005; EP 20870870 A 20201005; JP 2022520713 A 20201005;
KR 20227014905 A 20201005; US 202017657850 A 20201005